

MC74AC253, MC74ACT253

Dual 4-Input Multiplexer with 3-State Outputs

The MC74AC253/74ACT253 is a dual 4-input multiplexer with 3-state outputs. It can select two bits of data from four sources using common select inputs. The outputs may be individually switched to a high impedance state with a HIGH on the respective Output Enable ($\overline{OE}$) inputs, allowing the outputs to interface directly with bus oriented systems.

- Multifunctional Capability
- Noninverting 3-State Outputs
- Outputs Source/Sink 24 mA
- 'ACT253 Has TTL Compatible Inputs
- These are Pb-Free Devices

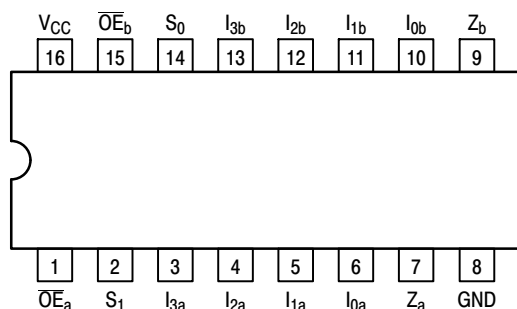


Figure 1. Pinout: 16-Lead Packages Conductors (Top View)

PIN NAME

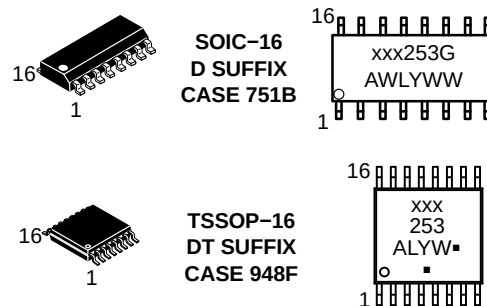
PIN	FUNCTION
I_{0a} – I_{3a}	Side A Data Inputs
I_{0b} – I_{3b}	Side B Data Inputs
S_0 , S_1	Common Select Inputs
$\overline{OE}_a$	Side A Output Enable Input
$\overline{OE}_b$	Side B Output Enable Input
Z_a , Z_b	3-State Outputs



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MARKING DIAGRAMS



xxx = AC or ACT
A = Assembly Location
WL or L = Wafer Lot
Y = Year
WW or W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

MC74AC253, MC74ACT253

TRUTH TABLE

Select Inputs		Data Inputs				Output Enable	Outputs
S ₀	S ₁	I ₀	I ₁	I ₂	I ₃	$\overline{OE}$	Z
X	X	X	X	X	X	H	Z
L	L	L	X	X	X	L	L
L	L	H	X	X	X	L	H
H	L	X	L	X	X	L	L
H	L	X	H	X	X	L	H
L	H	X	X	L	X	L	L
L	H	X	X	H	X	L	H
H	H	X	X	X	L	L	L
H	H	X	X	X	H	L	H

Address inputs S₀ and S₁ are common to both sections.

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

FUNCTIONAL DESCRIPTION

The MC74AC253/74ACT253 contains two identical 4-input multiplexers with 3-state outputs. They select two bits from four sources selected by common Select inputs (S₀, S₁). The 4-input multiplexers have individual Output Enable ($\overline{OE_a}$, $\overline{OE_b}$) inputs which, when HIGH, force the outputs to a high impedance (High Z) state. This device is the logic implementation of a 2-pole, 4-position switch, where the position of the switch is determined by the logic levels

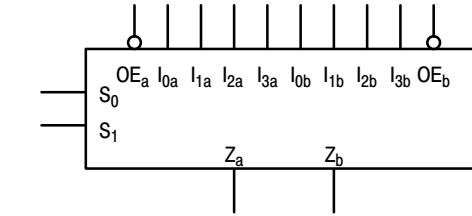


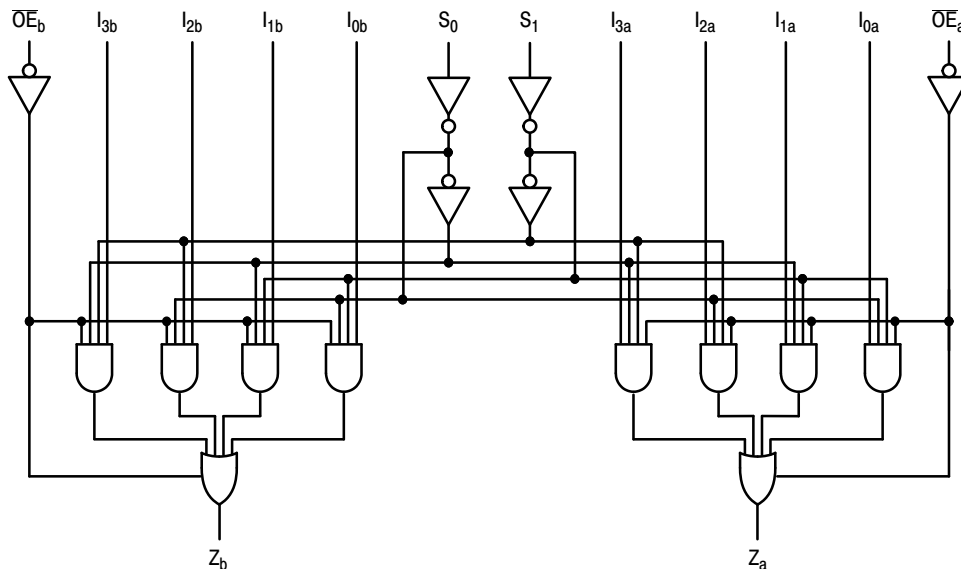
Figure 2. Logic Symbol

supplied to the two select inputs. The logic equations for the outputs are shown:

$$Z_a = \overline{OE_a} \cdot (I_{0a} \cdot \overline{S_1} \cdot \overline{S_0} + I_{1a} \cdot \overline{S_1} \cdot S_0 + I_{2a} \cdot S_1 \cdot \overline{S_0} + I_{3a} \cdot S_1 \cdot S_0)$$

$$Z_b = \overline{OE_b} \cdot (I_{0b} \cdot \overline{S_1} \cdot \overline{S_0} + I_{1b} \cdot \overline{S_1} \cdot S_0 + I_{2b} \cdot S_1 \cdot \overline{S_0} + I_{3b} \cdot S_1 \cdot S_0)$$

If the outputs of 3-state devices are tied together, all but one device must be in the high impedance state to avoid high currents that would exceed the maximum ratings. Designers should ensure that Output Enable signals to 3-state devices whose outputs are tied together are designed so that there is no overlap.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MC74AC253, MC74ACT253

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	−0.5 to +7.0	V
V _I	DC Input Voltage	−0.5 ≤ V _{CC} +0.5	V
V _O	DC Output Voltage (Note 1)	−0.5 ≤ V _{CC} +0.5	V
I _{IK}	DC Input Diode Current	±20	mA
I _{OK}	DC Output Diode Current	±50	mA
I _O	DC Output Sink/Source Current	±50	mA
I _{CC}	DC Supply Current per Output Pin	±50	mA
I _{GND}	DC Ground Current per Output Pin	±50	mA
T _{STG}	Storage Temperature Range	−65 to +150	°C
T _L	Lead temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction temperature under Bias	+150	°C
θ _{JA}	Thermal Resistance (Note 2) SOIC TSSOP	69.1 103.8	°C/W
P _D	Power Dissipation in Still Air at 65°C (Note 3) SOIC TSSOP	500 500	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 30% – 35%	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 4) Machine Model (Note 5) Charged Device Model (Note 6)	> 2000 > 200 > 1000	V
I _{Latch-Up}	Latch-Up Performance Above V _{CC} and Below GND at 85°C (Note 7)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.
2. The package thermal impedance is calculated in accordance with JEDEC51-7.
3. 500 mW at 65°C; derate to 300 mW by 10 mW/°C from 65°C to 85°C.
4. Tested to EIA/JESD22-A114-A.
5. Tested to EIA/JESD22-A115-A.
6. Tested to JEDEC22-C101-A.
7. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit
V _{CC}	Supply Voltage	'AC	2.0	5.0	V
		'ACT	4.5	5.0	
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)	0	–	V _{CC}	V
t _r , t _f	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V _{CC} @ 3.0 V	–	150	ns/V
		V _{CC} @ 4.5 V	–	40	
		V _{CC} @ 5.5 V	–	25	
t _r , t _f	Input Rise and Fall Time (Note 2) 'ACT Devices except Schmitt Inputs	V _{CC} @ 4.5 V	–	10	ns/V
		V _{CC} @ 5.5 V	–	8.0	
T _A	Operating Ambient Temperature Range	−40	25	85	°C
I _{OH}	Output Current – High	–	–	−24	mA
I _{OL}	Output Current – Low	–	–	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

MC74AC253, MC74ACT253

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74AC		74AC	Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C		
			Typ	Guaranteed Limits			
V _{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V _{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V _{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I _{OUT} = -50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	-	2.56	2.46	V	*V _{IN} = V _{IL} or V _{IH} -12 mA I _{OH} -24 mA -24 mA
		4.5	-	3.86	3.76		
		5.5	-	4.86	4.76		
V _{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I _{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	-	0.36	0.44	V	*V _{IN} = V _{IL} or V _{IH} 12 mA I _{OL} 24 mA 24 mA
		4.5	-	0.36	0.44		
		5.5	-	0.36	0.44		
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μA	V _I = V _{CC} , GND
I _{OZ}	Maximum 3-State Current	5.5	-	±0.5	±5.0	μA	V _I (OE) = V _{IL} , V _{IH} V _I = V _{CC} , GND V _O = V _{CC} , GND
I _{OLD}	†Minimum Dynamic Output Current	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}		5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80	μA	V _{IN} = V _{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

MC74AC253, MC74ACT253

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V _{CC} * (V)	74AC			74AC		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
t _{PLH}	Propagation Delay S _n to Z _n	3.3 5.0	2.0 2.0	– –	15.5 11.0	2.0 1.5	17.5 12.5	ns	3–6
t _{PHL}	Propagation Delay S _n to Z _n	3.3 5.0	2.5 2.0	– –	16.0 11.5	2.0 1.5	18.0 13.0	ns	3–6
t _{PLH}	Propagation Delay I _n to Z _n	3.3 5.0	1.5 1.5	– –	14.5 10.0	1.5 1.5	17.0 11.5	ns	3–5
t _{PHL}	Propagation Delay I _n to Z _n	3.3 5.0	2.0 1.5	– –	13.0 9.5	1.5 1.5	15.0 11.0	ns	3–5
t _{PZH}	Output Enable Time	3.3 5.0	1.5 1.5	– –	8.0 6.0	1.0 1.0	8.5 6.5	ns	3–7
t _{PZL}	Output Enable Time	3.3 5.0	1.5 1.5	– –	8.0 6.0	1.0 1.0	9.0 7.0	ns	3–8
t _{PHZ}	Output Disable Time	3.3 5.0	2.0 2.0	– –	9.5 8.0	1.5 1.5	10.0 8.5	ns	3–7
t _{PLZ}	Output Disable Time	3.3 5.0	1.5 1.5	– –	8.0 7.0	1.0 1.0	9.0 7.5	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

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DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74ACT		74ACT	Unit	Conditions
			T _A = +25°C		T _A = −40°C to +85°C		
			Typ	Guaranteed Limits			
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V _{OUT} = 0.1 V or V _{CC} − 0.1 V
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V _{OUT} = 0.1 V or V _{CC} − 0.1 V
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I _{OUT} = −50 μA
		4.5 5.5	− −	3.86 4.86	3.76 4.76	V	*V _{IN} = V _{IL} or V _{IH} −24 mA I _{OH} −24 mA
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I _{OUT} = 50 μA
		4.5 5.5	− −	0.36 0.36	0.44 0.44	V	*V _{IN} = V _{IL} or V _{IH} 24 mA I _{OL} 24 mA
I _{IN}	Maximum Input Leakage Current	5.5	−	±0.1	±1.0	μA	V _I = V _{CC} , GND
ΔI _{CCT}	Additional Max. I _{CC} /Input	5.5	0.6	−	1.5	mA	V _I = V _{CC} − 2.1 V
I _{OZ}	Maximum 3-State Current	5.5	−	±0.5	±5.0	μA	V _I (OE) = V _{IL} , V _{IH} V _I = V _{CC} , GND V _O = V _{CC} , GND
I _{OLD}	†Minimum Dynamic Output Current	5.5	−	−	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}		5.5	−	−	−75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	−	8.0	80	μA	V _{IN} = V _{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

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AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V _{CC} * (V)	74ACT			74ACT		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
t _{PLH}	Propagation Delay S _n to Z _n	5.0	2.0	–	11.5	2.0	13.0	ns	3–6
t _{PHL}	Propagation Delay S _n to Z _n	5.0	3.0	–	13.0	2.5	14.5	ns	3–6
t _{PLH}	Propagation Delay I _n to Z _n	5.0	2.5	–	10.0	2.0	11.0	ns	3–5
t _{PHL}	Propagation Delay I _n to Z _n	5.0	3.5	–	11.0	3.0	12.5	ns	3–5
t _{PZH}	Output Enable Time	5.0	2.0	–	7.5	1.5	8.5	ns	3–7
t _{PZL}	Output Enable Time	5.0	2.0	–	8.0	1.5	9.0	ns	3–8
t _{PHZ}	Output Disable Time	5.0	3.0	–	9.5	2.5	10.0	ns	3–7
t _{PLZ}	Output Disable Time	5.0	2.5	–	7.5	2.0	8.5	ns	3–8

* Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	50	pF	V _{CC} = 5.0 V

ORDERING INFORMATION

Device Order Number	Package	Shipping†
MC74AC253DG	SOIC–16 (Pb–Free)	48 Units / Rail
MC74AC253DR2G	SOIC–16 (Pb–Free)	2500 Tape & Reel
MC74AC253DTR2G	TSSOP–16 (Pb–Free)	2500 Tape & Reel
MC74ACT253DG	SOIC–16 (Pb–Free)	48 Units / Rail
MC74ACT253DR2G	SOIC–16 (Pb–Free)	2500 Tape & Reel
MC74ACT253DTR2G	TSSOP–16 (Pb–Free)	2500 Tape & Reel

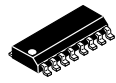
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

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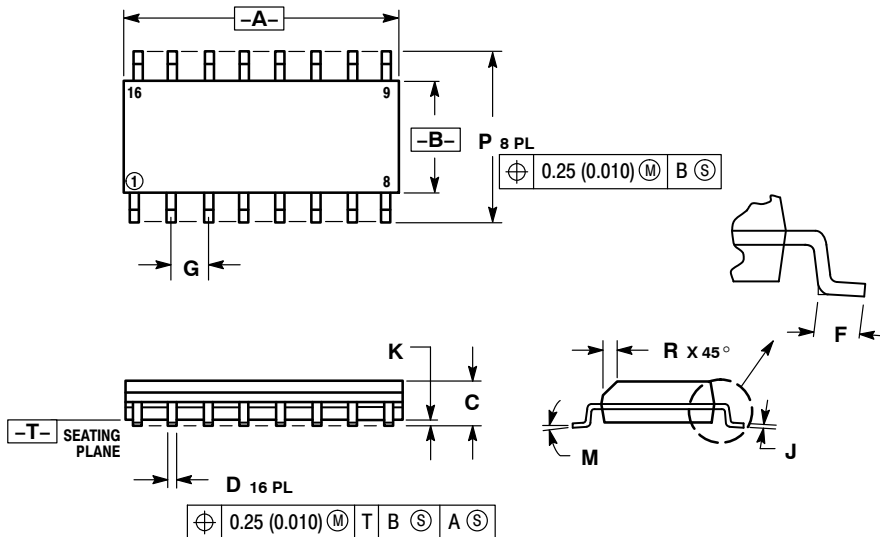
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SCALE 1:1

SOIC-16 CASE 751B-05 ISSUE K

DATE 29 DEC 2006



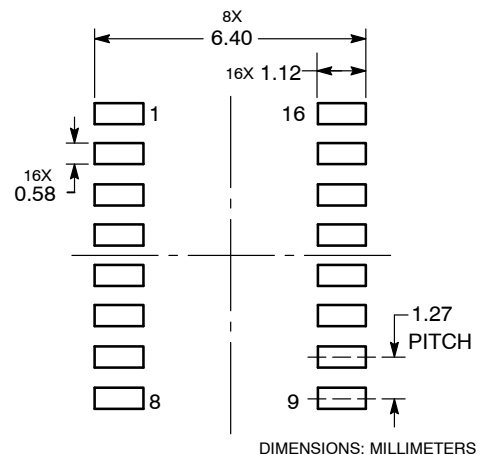
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:
PIN 1. COLLECTOR	PIN 1. CATHODE	PIN 1. COLLECTOR, DYE #1	PIN 1. COLLECTOR, DYE #1
2. BASE	2. ANODE	2. BASE, #1	2. COLLECTOR, #1
3. EMITTER	3. NO CONNECTION	3. EMITTER, #1	3. COLLECTOR, #2
4. NO CONNECTION	4. CATHODE	4. COLLECTOR, #1	4. COLLECTOR, #2
5. EMITTER	5. CATHODE	5. COLLECTOR, #2	5. COLLECTOR, #3
6. BASE	6. NO CONNECTION	6. BASE, #2	6. COLLECTOR, #3
7. COLLECTOR	7. ANODE	7. EMITTER, #2	7. COLLECTOR, #4
8. COLLECTOR	8. CATHODE	8. COLLECTOR, #2	8. COLLECTOR, #4
9. BASE	9. CATHODE	9. COLLECTOR, #3	9. BASE, #4
10. EMITTER	10. ANODE	10. BASE, #3	10. EMITTER, #4
11. NO CONNECTION	11. NO CONNECTION	11. EMITTER, #3	11. BASE, #3
12. EMITTER	12. CATHODE	12. COLLECTOR, #3	12. EMITTER, #3
13. BASE	13. CATHODE	13. COLLECTOR, #4	13. BASE, #2
14. COLLECTOR	14. NO CONNECTION	14. BASE, #4	14. EMITTER, #2
15. EMITTER	15. ANODE	15. EMITTER, #4	15. BASE, #1
16. COLLECTOR	16. CATHODE	16. COLLECTOR, #4	16. EMITTER, #1
STYLE 5:	STYLE 6:	STYLE 7:	
PIN 1. DRAIN, DYE #1	PIN 1. CATHODE	PIN 1. SOURCE N-CH	
2. DRAIN, #1	2. CATHODE	2. COMMON DRAIN (OUTPUT)	
3. DRAIN, #2	3. CATHODE	3. COMMON DRAIN (OUTPUT)	
4. DRAIN, #2	4. CATHODE	4. GATE P-CH	
5. DRAIN, #3	5. CATHODE	5. COMMON DRAIN (OUTPUT)	
6. DRAIN, #3	6. CATHODE	6. COMMON DRAIN (OUTPUT)	
7. DRAIN, #4	7. CATHODE	7. COMMON DRAIN (OUTPUT)	
8. DRAIN, #4	8. CATHODE	8. SOURCE P-CH	
9. GATE, #4	9. ANODE	9. SOURCE P-CH	
10. SOURCE, #4	10. ANODE	10. COMMON DRAIN (OUTPUT)	
11. GATE, #3	11. ANODE	11. COMMON DRAIN (OUTPUT)	
12. SOURCE, #3	12. ANODE	12. COMMON DRAIN (OUTPUT)	
13. GATE, #2	13. ANODE	13. GATE N-CH	
14. SOURCE, #2	14. ANODE	14. COMMON DRAIN (OUTPUT)	
15. GATE, #1	15. ANODE	15. COMMON DRAIN (OUTPUT)	
16. SOURCE, #1	16. ANODE	16. SOURCE N-CH	

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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